

## **Product Change Notification - CYER-11SNTE468**

Date: 14 Jul 2011

Product Category: Analog (Thermal, Power Management & Safety)

Device Family:

Notification subject: CCB 1070: Qualification of 3L SOT-89 with full Ag platting on the lead-frame at HANA assembly site.

Notification text:

PCN Status: Initial notification

Microchip Parts Affected:

See attachments of affected catalog part numbers (CPN) labeled as...

PCN\_CYER-11SNTE468\_Affected\_CPN.xls PCN\_CYER-11SNTE468\_Affected\_CPN.pdf

Description of Change:

Qualification of 3L SOT-89 with Ag platting on the entire lead-frame at HANA assembly site.

Pre Change:

Ag ring plating on Lead-frame

Post Change:

Full Ag plating on Lead-frame

Impacts to Data Sheet:

None

Reason for Change:

To improve on time delivery performance

Change Implementation Status:

In Progress

Estimated First Ship Date:

September 30, 2011 (date code: 1140)

NOTE: Please be advised that during the transition period customers may receive pre and post change parts,

due to existing inventory of the pre changed parts.

Markings to Distinguish Revised from Unrevised Devices:

Traceability code

Revision History:

July 14, 2011: Issued initial notification.

Attachment(s):

PCN\_CYER-11SNTE468\_Affected\_CPN.pdf PCN\_CYER-11SNTE468\_Affected\_CPN.xls PCN\_CYER-11SNTE468\_Qual Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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CYER-11SNTE468	- CCB 1070: Qualification of 3L SOT-89 with full Ag platting on the lead-frame at HANA assembly site.
Parts Affected	
MCP111	
MCP112	
MCP1700	
MCP1702	
MCP1703	

Date: Thursday, July 14, 2011